

IN THE SPECIFICATION:

Please note that the paragraphs shown below are in clean form for clarity.

Please replace the paragraph bridging pages 3 and 4 with the following:

E2
In United States Patent 5,620,927 of Lee, a template with an array of through-holes is placed on the workpiece and solder balls are introduced into the holes by rolling the solder balls across the workpiece surface. The apparatus may be installed on a tilt table to encourage filling of all holes. In United States Patent 4,871,110 of Fukasawa et al., a template having an array of holes is placed on a ball holder with a like array of smaller holes to which vacuum is applied and over which solder balls are rolled. After the array is filled with solder balls, the template and ball holder with balls are removed and the exposed ends of the balls are attached to a substrate by e.g. reflow. The template and ball holder are then pulled from the substrate, leaving a ball-grid-array ready for attachment to another substrate or workpiece.

Please replace the fifth full paragraph on page 6 with the following:

E3
FIG. 11A is a sectional side view of a substrate in a process of having a ball-grid-array formed thereon in a method of another embodiment of the invention wherein the substrate holder includes a screen thereon;

Please replace the third full paragraph on page 7 with the following:

E4
As shown in FIG. 3, a solder ball reservoir 30 is configured to hold a large number of preformed solder balls 60 and has gas sparge holes 54 for fluidizing the balls within the reservoir, whereby the balls are attracted to and held by vacuum suction in the ball seats 36. Other alternative (or additional) means for fluidizing the balls 60 may be used, such as a vibrator 63.